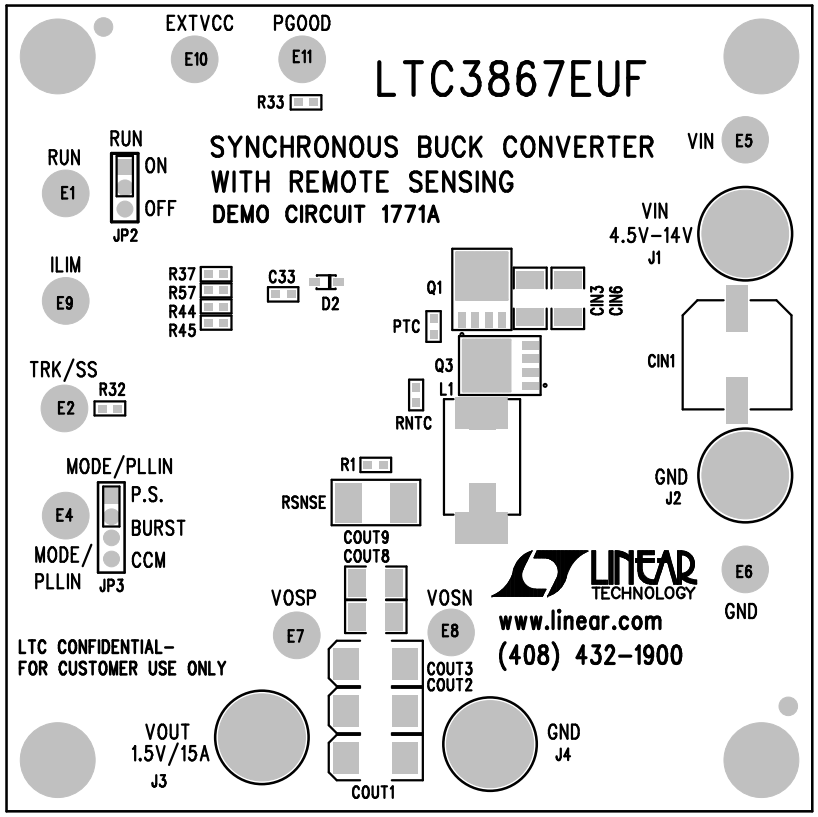
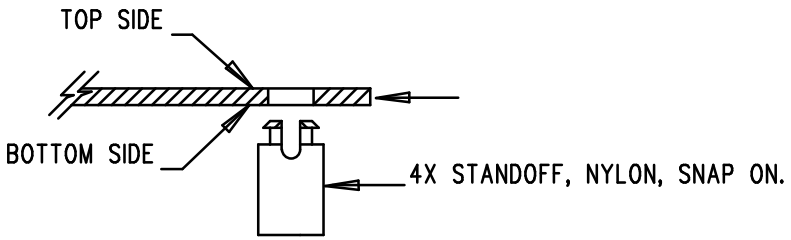
REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
–	2	2nd PROTOTYPE	DING L.	2-14-11



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC–A–610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER SIDE SMD.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE–OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



8. MAXIMUM SOLDER TEMPERATURE 240 DEGREE(C).

APPROVALS	
PCB DES.	HZ
APP ENG.	DING L.
SCALE = NONE	

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TITLE: TOP ASSEMBLY DRAWING
SYNCHRONOUS BUCK CONVERTER
WITH REMOTE SENSING

SIZE	IC NO.	REV.
N/A	LTC3867EUF DEMO CIRCUIT 1771A	2

FILENAME: DC1771A–2.PCB | SHT 1 OF 2